

Title (en)

Electrolytic bath for the deposition of palladium and palladium alloys

Title (de)

Elektrolytisches Bad zum Abscheiden von Palladium und von Legierungen des Palladiums

Title (fr)

Bain électrolytique pour le dépôt de palladium et d'alliages de palladium

Publication

**EP 0916747 B1 20021016 (DE)**

Application

**EP 98121772 A 19981116**

Priority

- DE 19750575 A 19971115
- DE 19803818 A 19980131

Abstract (en)

[origin: EP0916747A1] An electrolyte bath for the deposition of palladium and palladium alloys comprises an aqueous solution of (A) 1-50 g/l of a palladium as a chloride, sulfate, nitrate or nitrite complex (B) a conductive salt (C) a brightening agent, preferably N-(3-sulfopropyl)- pyridium betaine (D) a cross-linking agent and (E) 0.01-3 g/l sulfite ( $\text{SO}_3^{2-}$ ) and has a pH of 6-9.5.

IPC 1-7

**C25D 3/52**; **C25D 3/56**

IPC 8 full level

**C25D 3/52** (2006.01); **C25D 3/56** (2006.01)

CPC (source: EP)

**C25D 3/52** (2013.01); **C25D 3/567** (2013.01)

Citation (examination)

- US 3933602 A 19760120 - HENZI RENE, et al
- J.K. DENNIS AND T.E. SUCH: "Nickel and Chromium Plating", 1972, NEWNES-BUTTERWORTHS, LONDON

Cited by

EP3964610A1; CN1113981C

Designated contracting state (EPC)

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